

CM75TU-12F

HIGH POWER SWITCHING USE

MAXIMUM RATINGS (Tj = 25°C, unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-emitter voltage	G-E Short	600	V
V _{GES}	Gate-emitter voltage	C-E Short	±20	V
I _C	Collector current	T _C = 25°C	75	A
I _{CM}		Pulse (Note 2)	150	
I _E (Note 1)	Emitter current	T _C = 25°C	75	A
I _{EM} (Note 1)		Pulse (Note 2)	150	
P _C (Note 3)	Maximum collector dissipation	T _C = 25°C	290	W
T _j	Junction temperature		-40 ~ +150	°C
T _{stg}	Storage temperature		-40 ~ +125	°C
V _{iso}	Isolation voltage	Terminals to base plate, f = 60Hz, AC 1 minute	2500	V _{rms}
—	Torque strength	Main terminals M4 screw	1.3 ~ 1.7	N · m
—		Mounting M5 screw	2.5 ~ 3.5	N · m
—	Weight	Typical value	570	g

ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise specified)

Symbol	Parameter	Test conditions	Limits			Unit	
			Min.	Typ.	Max.		
I _{CES}	Collector cutoff current	V _{CE} = V _{CES} , V _{GE} = 0V	—	—	1	mA	
V _{GE(th)}	Gate-emitter threshold voltage	I _C = 7.5mA, V _{CE} = 10V	5	6	7	V	
I _{GES}	Gate leakage current	±V _{GE} = V _{GES} , V _{CE} = 0V	—	—	20	µA	
V _{CE(sat)}	Collector-emitter saturation voltage	I _C = 75A, V _{GE} = 15V	T _j = 25°C	—	1.6	2.2	V
			T _j = 125°C	—	1.6	—	
C _{ies}	Input capacitance	V _{CE} = 10V V _{GE} = 0V	—	—	20	nF	
C _{oes}	Output capacitance		—	—	1.4		
C _{res}	Reverse transfer capacitance		—	—	0.75		
Q _G	Total gate charge	V _{CC} = 300V, I _C = 75A, V _{GE} = 15V	—	465	—	nC	
t _{d(on)}	Turn-on delay time	V _{CC} = 300V, I _C = 75A V _{GE} = ±15V R _G = 8.3Ω, Inductive load I _E = 75A	—	—	100	ns	
t _r	Turn-on rise time		—	—	80		
t _{d(off)}	Turn-off delay time		—	—	300		
t _f	Turn-off fall time		—	—	250		
t _{rr} (Note 1)	Reverse recovery time		—	—	150		
Q _{rr} (Note 1)	Reverse recovery charge		—	1.4	—		µC
V _{EC} (Note 1)	Emitter-collector voltage	I _E = 75A, V _{GE} = 0V	—	—	2.6	V	
R _{th(j-c)Q}	Thermal resistance*1	IGBT part (1/6 module)	—	—	0.43	K/W	
R _{th(j-c)R}		FWDi part (1/6 module)	—	—	0.9		
R _{th(c-f)}	Contact thermal resistance	Case to heat sink, Thermal compound applied*2 (1/6 module)	—	0.11	—		
R _{th(j-c)Q}	Thermal resistance	Case temperature measured point is just under the chips	—	—	0.34*3		
R _G	External gate resistance		8.3	—	83	Ω	

Note 1. I_E, V_{EC}, t_{rr}, Q_{rr} & die/dt represent characteristics of the anti-parallel, emitter-collector free-wheel diode (FWDi).

2. Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed T_{jmax} rating.

3. Junction temperature (T_j) should not increase beyond 150°C.

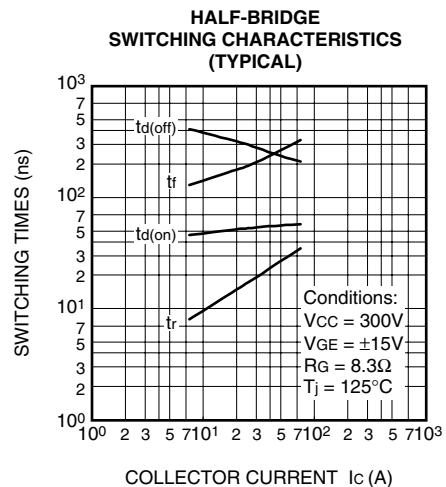
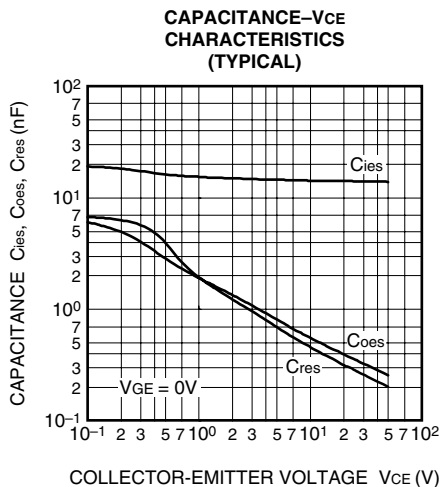
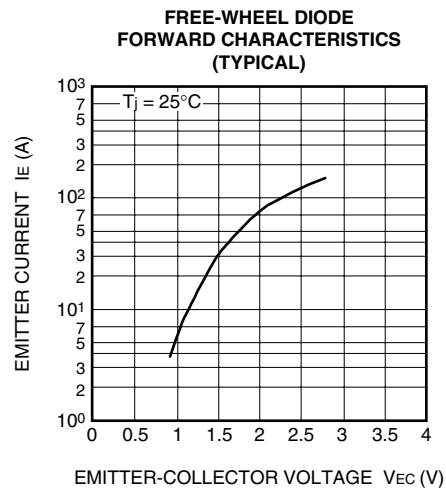
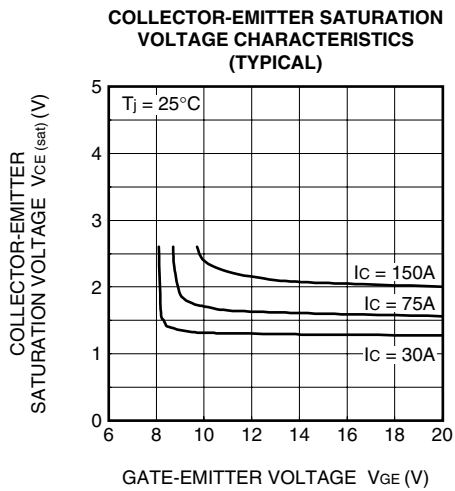
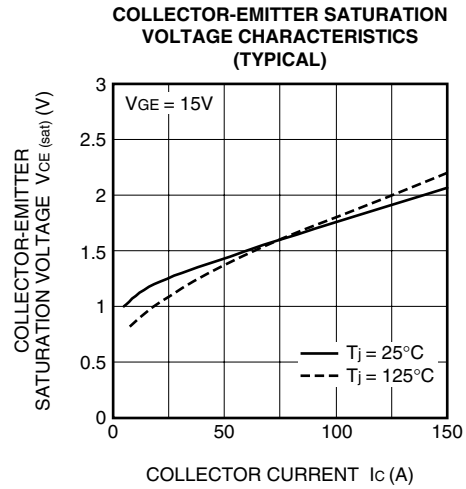
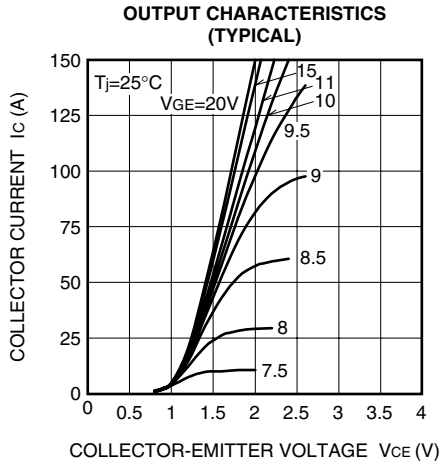
4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

*1 : Case temperature (T_c) measured point is indicated in OUTLINE DRAWING.

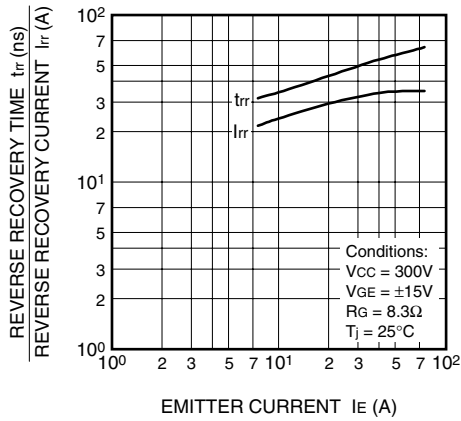
*2 : Typical value is measured by using thermally conductive grease of λ = 0.9[W/(m · K)].

*3 : If you use this value, R_{th(f-a)} should be measured just under the chips.

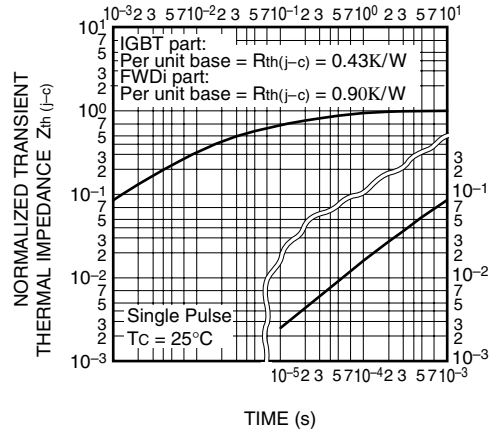
PERFORMANCE CURVES



REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



GATE CHARGE CHARACTERISTICS (TYPICAL)

